

October 2019

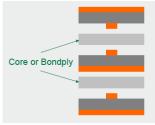
Eltek Teflon (PTFE) Fusion Bonding

1. Benefits of the Teflon (PTFE) Fusion Bonding

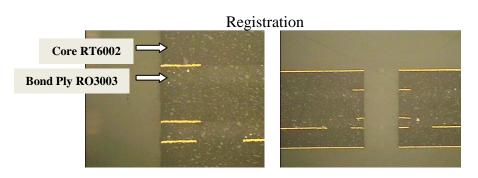
- ✓ Homogenous multi-layer constructions using high performance materials.
- ✓ High electrical performance compare to other lamination methods. The same Dk, Df for core and bond ply.
- ✓ Improved layer-layer registration as compared to MLB's bonded using non-PTFE prepreg or unfiled fluopolymer films.
- ✓ Excellent dielectric layer to layer adhesion.
- ✓ Highly reliable PTH structure.

2. Eltek Capability (Teflon) PTFE Fusion Bonding:

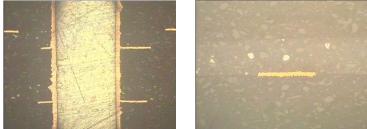
- ✓ Panel Size 12"x18"
- ✓ Teflon (PTFE) based core Material
- ✓ Bond Ply Multilayer Stack
- ✓ High Thermal Stress Reliability



3. Test Eltek samples of Teflon (PTFE) Fusion Bonding, Rigid Board:



After 6 Thermal Stress @IPC TM-650 2.6.8 Thermal Stress, Plated-Through Holes



4. Conclusion

Eltek has internally approved the technology of the Teflon (PTFE) fusion bonding with the method "Bond Ply MLB Stack" in the production of multilayer PCB.

